

## AMD's Silicon-Level Innovation Priorities through 2008

### Chipsets

- DDR3, DDR4, FBDIMM, FBD2
- System resource management
- Mainframe class reliability
- Broader client support

### Peripheral Interfaces

- PCI Express
- HyperTransport™ technology 3.0 and 4.0
- Systems management ports

### Third-Party Silicon Solutions

- HORUS 32-processor system capability
- Off-chip coprocessors
- FPGA

- Enhanced chipset technologies for next-generation functionality
- Expanded interface options and improved throughput for better overall system performance
- Third-party silicon solutions for best-of-breed capabilities